

REMARKS

Claims 1 through 12 are currently pending in the application.

Claims 2 and 4 through 12 have been withdrawn from consideration as being directed to a non-elected invention.

This amendment is in response to the Office Action of November 15, 2002.

Drawings

Applicants submit herewith, under cover of a separate Submission of Proposed Drawing Amendment, for proposed corrections to FIGS. 6 and 7 of the drawings. All proposed corrections have been marked in red. A Transmittal of Formal Drawings is included with formal drawing FIGS. 6 and 7 with proposed changes.

Specification

The title of the invention was objected to as not being descriptive and as not being clearly indicative of the invention to which the claims are directed. Appropriate correction has been made.

35 U.S.C. § 101 Double Patenting Rejection

Claims 1 and 3 were rejected under 35 U.S.C. § 101 as claiming the same invention as that of claims 1 and 3 of prior U.S. Patent 6,316,824 (hereinafter referred to as the '824 patent). Applicants respectfully traverse this rejection, as hereinafter set forth.

Applicants submit that a reliable test for statutory double patenting under 35 U.S.C. § 101 is whether a claim in the application can be literally infringed without literally infringing a corresponding claim in the patent. Is there an embodiment of the invention that falls within the scope of one claim, but not the other? If there is such an embodiment of the invention, then identical subject matter is not defined by both claims and statutory double patenting under 35 U.S.C. § 101 does not exist. *In re Vogel*, 422 F.2d 438, 164 USPQ 619 (CCPA 1970).

Applicants submit that in the present instance, no statutory double patenting under 35 U.S.C. § 101 exists between the presently claimed invention of amended independent claims 1

and 3 of the present application and independent claims 1 and 3 of the '824 patent. Further, in presently amended independent claims 1 and 3 of the present application an embodiments of the inventions are claimed having an element of the invention calling for "an integrated circuit semiconductor die . . . for attachment in one of a conventional die attach to lead frame connect process and a LOC connect process" whereas the embodiments of the inventions set forth in claims 1 and 3 of the '824 patent do not. Accordingly, no statutory double patenting under 35 U.S.C. § 101 exists between the embodiments of the inventions claimed in presently amended independent claims 1 and 3 of the present application and claims 1 and 3 of the '824 patent. Therefore, claims 1 and 3 are allowable.

Applicants request the allowance of claims 1 and 3 and the case passed for issue.

Respectfully submitted,



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JRD/jml

Enclosure: Version with Markings to Show Changes Made

Document in ProLaw

VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE TITLE:

A marked-up version of the amended title, highlighting the changes thereto, follows to clearly identify the amendments:

PLASTIC LEAD FRAMES FOR SEMICONDUCTOR DEVICES[, PACKAGES
INCLUDING SAME, AND METHODS OF FABRICATION]

IN THE CLAIMS:

A marked-up version of each of the presently amended claims, highlighting the changes thereto, follows:

1. (Previously Amended) An electronic device comprising:
an integrated circuit semiconductor die having at least one bond pad thereon for attachment in one of a conventional die attach to lead frame connect process and a LOC connect process;
a conductive plastic lead frame having a plurality of lead fingers, said conductive plastic lead frame formed by one of compression molding and injection molding;
an adhesive attaching a portion of said integrated circuit semiconductor die to a portion of said conductive plastic lead frame;
at least one connector connecting said at least one bond pad of said integrated circuit semiconductor die to at least one lead finger of said plurality of lead fingers of said conductive plastic lead frame; and
encapsulating material for encapsulating at least a portion of said integrated circuit semiconductor die and for encapsulating at least a portion of at least one lead of said conductive plastic lead frame.

3. (Previously Amended) An electronic device comprising:
an integrated circuit semiconductor die having at least one bond pad thereon for attachment in one of a conventional die attach to lead frame connect process and a LOC connect process;
a conductive plastic lead frame having a plurality of lead fingers, said conductive plastic lead frame including a plastic lead frame structure having a conductive polymeric material located on at least a portion of said plurality of lead fingers;
an adhesive for attaching a portion of said integrated circuit semiconductor die to a portion of said conductive plastic lead frame;
at least one connector connecting said at least one bond pad of said integrated circuit semiconductor die to at least one lead finger of said conductive plastic lead frame; and

encapsulating material for encapsulating at least a portion of said integrated circuit
semiconductor die and for encapsulating at least a portion of said at least one lead of said
conductive plastic lead frame.